

REMARKS/ARGUMENTS

Favorable reconsideration of this application as presently amended and in light of the following discussion is respectfully requested.

Claims 29, 31, 37 and 38 are pending in the present application. Claims 29 and 37 are amended and Claim 38 is added by the present amendment.

In the outstanding Office Action, Claim 29 was rejected under 35 U.S.C. §103(a) as unpatentable over Sugano et al. (U.S. Patent 5,198,888, herein "Sugano") in view of Fujimori (U.S. Patent 6,084,291); Claim 31 was rejected under 35 U.S.C. §103(a) as unpatentable over Sugano in view of Fujimori and Walter (U.S. Patent 4,770,640); and Claim 37 was rejected under 35 U.S.C. §103(a) as unpatentable over Sugano, Fujimori, and Lamson et al. (U.S. Patent 5,233,220, herein "Lamson").

Regarding the rejection of Claim 29 under 35 U.S.C. §103(a) as unpatentable over Sugano in view of Fujimori, independent Claim 29 has been amended to recite (i) at least a first pair of dummy lead wires and at least a second pair of dummy lead wires, (ii) two of the four sides are opposite to each other in a first direction and form first opposite sides, and the other two of the four sides are opposite to each other in a second direction and form second opposite sides, (iii) one and the other of the at least the first pair of dummy lead wires are provided on one and the other of the first opposite sides of the insulating film, respectively, and (iv) one and the other of the at least the second pair of dummy lead wires are provided on one and the other of the second opposite sides of the insulating film, respectively. The claim amendments find support in Figure 2A and its corresponding description in the specification. No new matter has been added.

Briefly recapitulating, independent Claim 29 is directed to a semiconductor apparatus that includes a semiconductor device, a plurality of lead wires, at least a first pair of dummy

lead wires and at least a second pair of dummy lead wires, an insulating film, and a resin molding. The insulating film has an opening portion that accommodates the semiconductor device and the opening portion has four sides that define a perimeter of the opening portion. Two of the four sides of the opening are opposite to each other in a first direction and form first opposite sides, and the other two of the four sides are opposite to each other in a second direction and form second opposite sides. One and the other of the at least the first pair of dummy lead wires are provided on one and the other of the first opposite sides of the opening, respectively, and one and the other of the at least the second pair of dummy lead wires are provided on one and the other of the second opposite sides of the insulating film, respectively.

In a non-limiting example, Figure 2A shows the first pair of dummy lead wires 13' and the second pair of dummy lead wires 13', each dummy lead wire being provided on a corresponding side of the opening 16 in the insulating film 12.

The outstanding Office Action recognizes at page 4, first full paragraph, that

Sugano et al. does not disclose the location of the one of the pair of dummy lead wires being placed on the opposite side surface of the plural side surfaces of said insulating film to correspond to the other one of the pair of dummy lead wires.

The outstanding Office Action relies on Fujimori for teaching the features lacking in Sugano. Fujimori shows in Figure 8 dummy leads 34a provided on only two opposite sides 30U of an opening 30 and no dummy lead wires on the other two opposite sides 30L. Thus, even the device of Sugano is modified using the teachings of Fujimori, the modified device would not have dummy lead wires on each of the four sides of the opening in the insulating film as required by amended Claim 29.

Accordingly, it is respectfully submitted that independent Claim 29 and each of the claims depending therefrom patentably distinguish over Sugano and Fujimori, either alone or in combination.

The remaining rejections of dependent Claims 31 and 37 under 35 U.S.C. §103(a) as unpatentable over various combinations of Sugano, Fujimori, Walter, and Lamson are respectfully traversed for the following reasons.

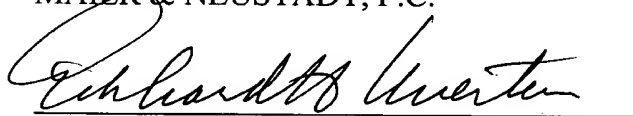
The outstanding Office Action relies on Walter for teaching a semiconductor chip in which a semiconductor device is formed with a thickness of approximately 50 μm , and on Lamson for teaching tip portions of at least a pair of dummy wires being connected to each other over a semiconductor device. However, neither Walter nor Lamson overcomes the deficiencies of Sugano and Fujimori discussed above regarding amended Claim 29. Accordingly, it is respectfully submitted that dependent Claims 31 and 37 are also allowable.

New Claim 38 has been added to set forth the invention in a varying scope and Applicant submits the new claim is supported by the originally filed specification. No new matter has been added. Accordingly, it is respectfully submitted new Claim 38 is allowable as it depends on independent Claim 29.

Consequently, in light of the above discussion and in view of the present amendment, the present application is believed to be in condition for allowance and an early and favorable action to that effect is respectfully requested.

Respectfully submitted,

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